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Docket No.: SHIG CFP03US013

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To the Director of the United States

103142562

Record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Yang JU

2. Name and address of receiving party(ies):

Name: TOHOKU TECHNO ARCH CO., LTD.

Address: 468, Aza Aoba, Aramaki, Aoba-ku, Sendai-shi

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

City: Miyagi

State/Prov.:

Country: JAPAN

ZIP:

Execution Date: October 5, 2005

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: 10/5/05

Patent Application No.

Filing date

B. Patent No.(s)

12/16/2005 MKAYPAGH 00000002 10559921

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Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Norman P. Soloway

Registration No. 24,315

Address: HAYES SOLOWAY P.C.

3450 E. Sunrise Drive, Suite 140

City: Tucson

State/Prov.: AZ

Country: USA

ZIP: 85718

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

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08-1391

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Norman P. Soloway

Name of Person Signing

Signature

December 8, 2005

Date

Total number of pages including cover sheet, attachments, and document:

3

ASSIGNMENT

(Foreign - in the United States of America)

I/we, **Yang JU**, of 1-2-301, 1-chome, Kunimi, Aoba-ku, Sendai-shi Miyagi 981-0943 JAPAN, having invented certain inventions and improvements in NONCONTACT CONDUCTIVITY MEASURING INSTRUMENT and having executed an application for Letters Patent of the United States of America describing the same and based thereon on the 5th day of October, 2005 (and I/we hereby authorize our attorneys to prosecute said application, to here insert the filing date and serial number of said application, when known, Serial No. _____, filed December 8, 2005), for good and valuable consideration, the receipt of which is hereby acknowledged from **TOHOKU TECHNO ARCH CO., LTD.**, a Japanese company having its principal place of business at 468, Aza Aoba, Aramaki, Aoba-ku, Sendai-shi, Miyagi JAPAN (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns our entire right, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or reissue application or applications and any patent which may be issued on the said invention in the United States of America;

And for the same consideration I/we do agree that I/we will upon request execute any instrument which the Assignee may desire to carry this Assignment into effect and perfect the title transferred hereby or prosecute the above-mentioned application;

And I/we do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent on the said application to the Assignee;

And I/we do hereby jointly and severally covenant for ourselves and for our legal representatives that I/we have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed my right, title, and interest in and to said inventions or any of them or any part thereof has not been otherwise encumbered by us, and that I/we have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, I/we hereunto set our hands and seals on the day and year hereinafter noted.

First Inventor's signature *Y. Ju* Date Oct. 5, 2005

Full name (typed or printed) Yang JU

Witness: *Hideo Shimizu* Witness: Hideo SHIMIZU

Date: Nov. 28, 2005 Date: November, 28, 2005